



Material Content Data Sheet



Sales Product Name		1EDN7550B		Issued		2. August 2018		
MA#		MA002753906						
Package		PG-SOT23-6-3		Weight*		18.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.480	2.58	2.58	25795	25795
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		117	
	non noble metal	zinc	7440-66-6	0.009	0.05		470	
	non noble metal	iron	7439-89-6	0.175	0.94		9396	
wires	non noble metal	copper	7440-50-8	7.097	38.15	39.15	381504	391487
	noble metal	palladium	7440-05-3	0.001	0.01		53	
	non noble metal	copper	7440-50-8	0.098	0.53	0.54	5263	5316
encapsulation	organic material	carbon black	1333-86-4	0.020	0.11		1055	
	plastics	epoxy resin	-	1.501	8.07		80684	
	inorganic material	silicondioxide	60676-86-0	8.289	44.55	52.73	445610	527349
leadfinish	non noble metal	tin	7440-31-5	0.465	2.50	2.50	24987	24987
plating	noble metal	silver	7440-22-4	0.175	0.94	0.94	9388	9388
glue	plastics	acrylic resin	-	0.064	0.34		3449	
	noble metal	silver	7440-22-4	0.227	1.22	1.56	12229	15678
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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